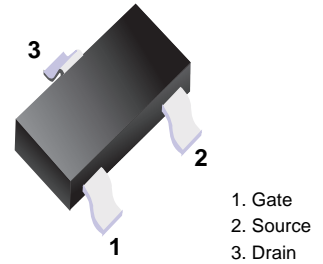
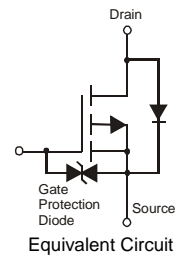


■ P-Channel Enhancement Mode MOSFET



■ Simplified outline(SOT-523)



■ Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 2)
- ESD Protected Up To 3kV

■ MARKING

Marking	PA1
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■ Absolute Maximum Ratings Ta = 25°C

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		$V_{DSS}$	-20	V	
Gate-Source Voltage		$V_{GSS}$	±6	V	
Drain Current (Note 1)	Steady State	$I_D$	$T_A = 25^\circ\text{C}$	-0.46	A
			$T_A = 85^\circ\text{C}$	-0.33	
Pulsed Drain Current		$I_{DM}$	-6	A	
Characteristic		Symbol	Value	Units	
Total Power Dissipation (Note 1)		$P_D$	0.27	W	
Thermal Resistance, Junction to Ambient		$R_{\theta JA}$	461	°C/W	
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	°C	

Notes: 1. Device mounted on FR-4 PCB.  
2. No purposefully added lead.

■ Electrical Characteristics Ta = 25°C

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 4)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C	I <sub>DSS</sub>	-	-	-100	nA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±2.0	μA	V <sub>GS</sub> = ±4.5V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 4)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.5	-	-1.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	0.5	0.7	Ω	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -350mA
			0.7	0.9		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -300mA
			1.0	1.3		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -150mA
Forward Transfer Admittance	Y <sub>fs</sub>	-	0.9	-	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -250mA
Diode Forward Voltage (Note 4)	V <sub>SD</sub>	-	-0.8	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -150mA
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>iss</sub>	-	59.76	-	pF	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	-	12.07	-	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	-	6.36	-	pF	
Total Gate Charge	Q <sub>g</sub>	-	622.4	-	pC	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, I <sub>D</sub> = -250mA
Gate-Source Charge	Q <sub>gs</sub>	-	100.3	-	pC	
Gate-Drain Charge	Q <sub>gd</sub>	-	132.2	-	pC	
Turn-On Delay Time	t <sub>D(on)</sub>	-	5.1	-	ns	V <sub>DD</sub> = -10V, V <sub>GS</sub> = -4.5V, R <sub>L</sub> = 47Ω, R <sub>G</sub> = 10Ω, I <sub>D</sub> = -200mA
Turn-On Rise Time	t <sub>r</sub>	-	8.1	-	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	28.4	-	ns	
Turn-Off Fall Time	t <sub>f</sub>	-	20.7	-	ns	

Notes: 4. Short duration pulse test used to minimize self-heating effect.

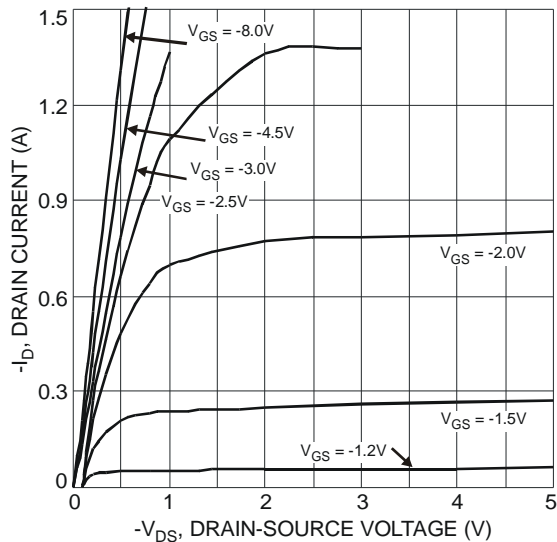


Fig. 1 Typical Output Characteristic

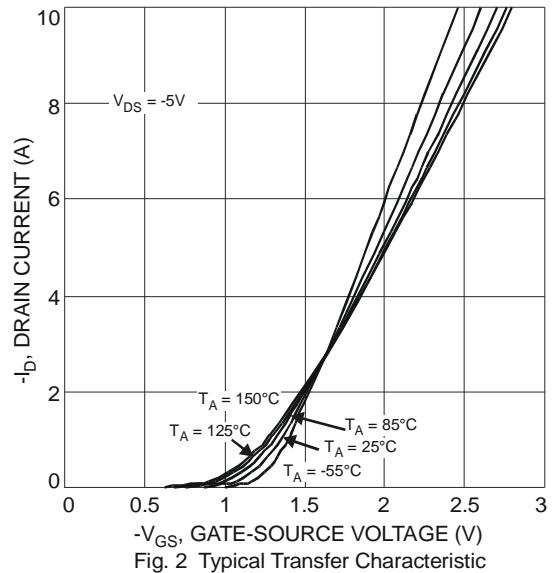
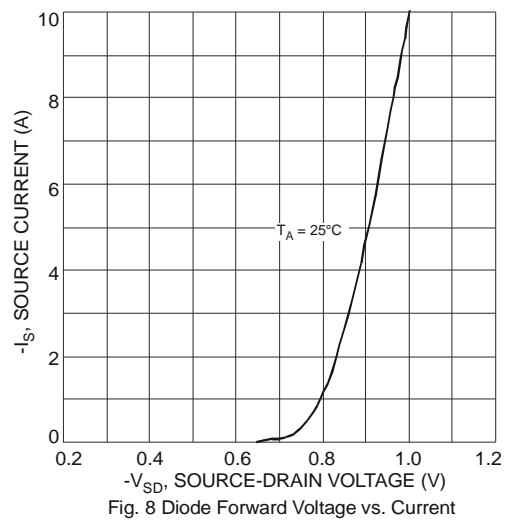
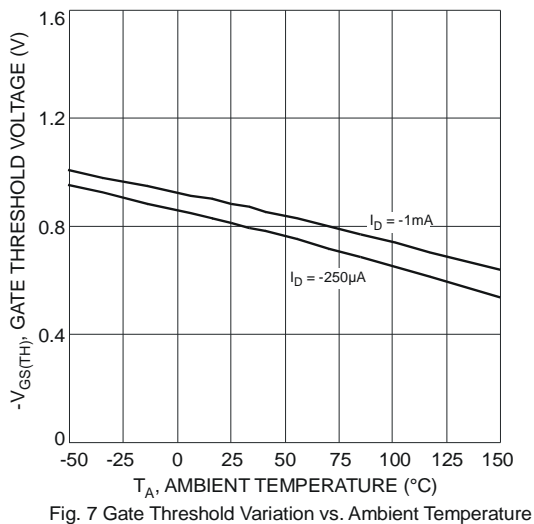
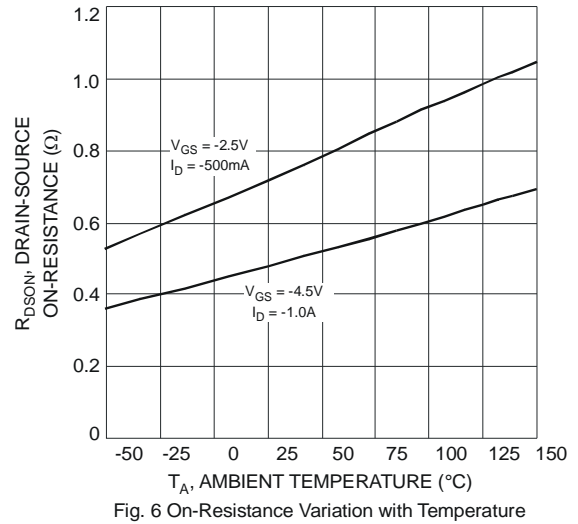
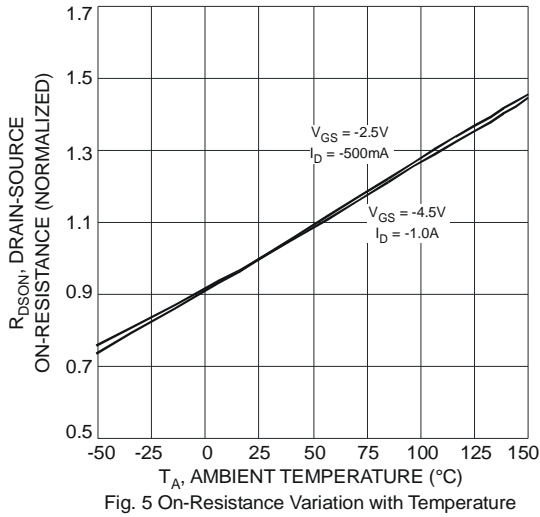
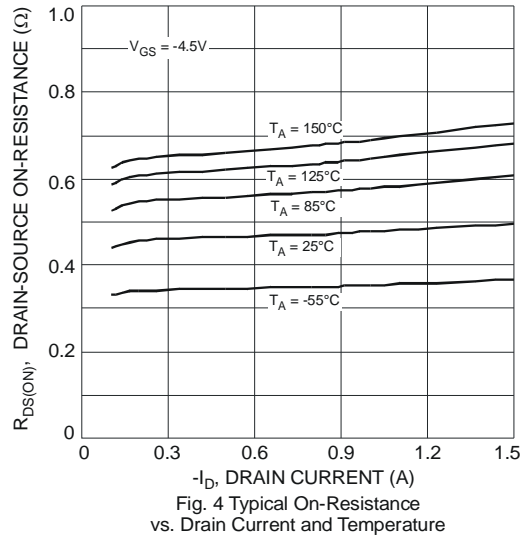
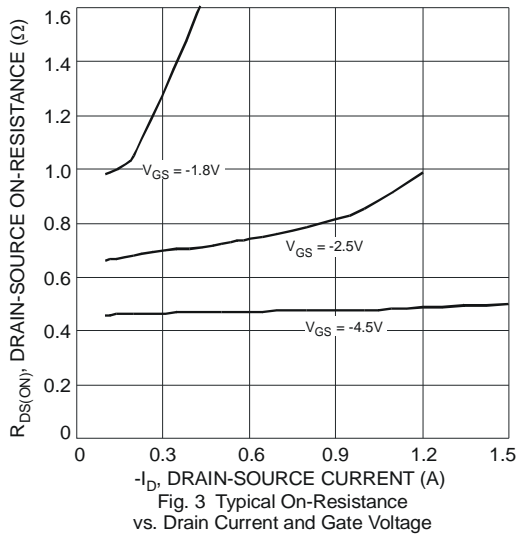


Fig. 2 Typical Transfer Characteristic



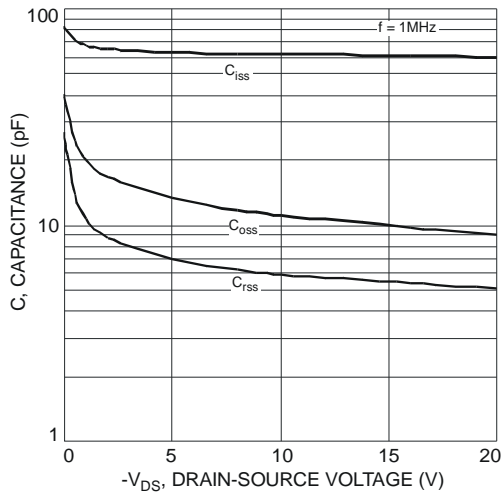


Fig. 9 Typical Total Capacitance

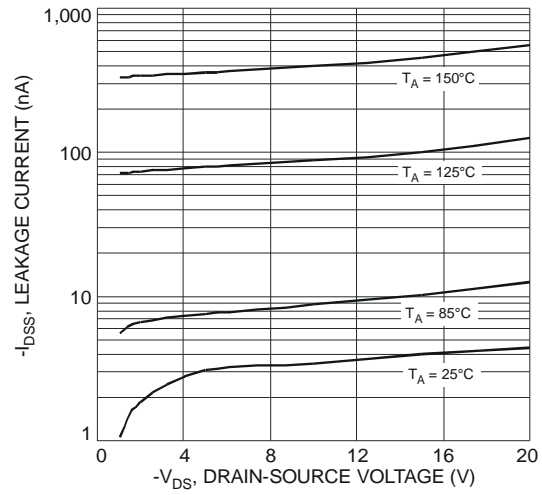


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

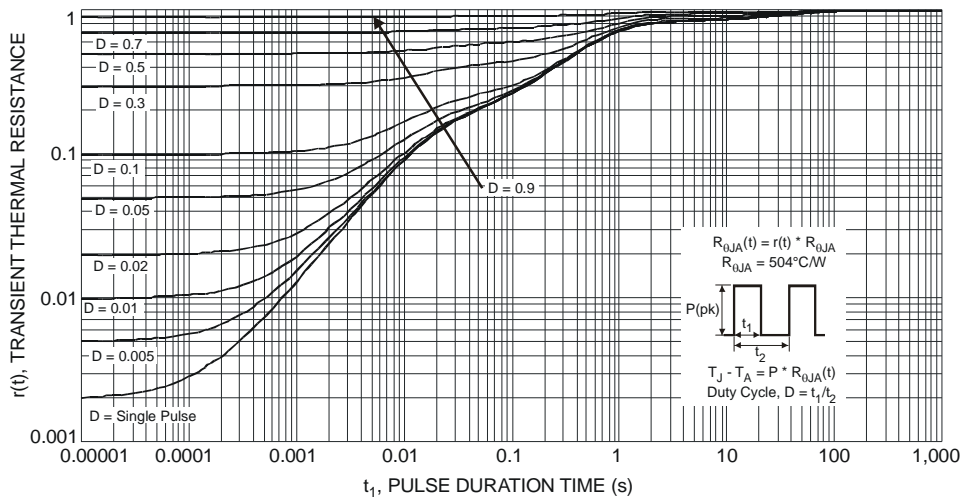
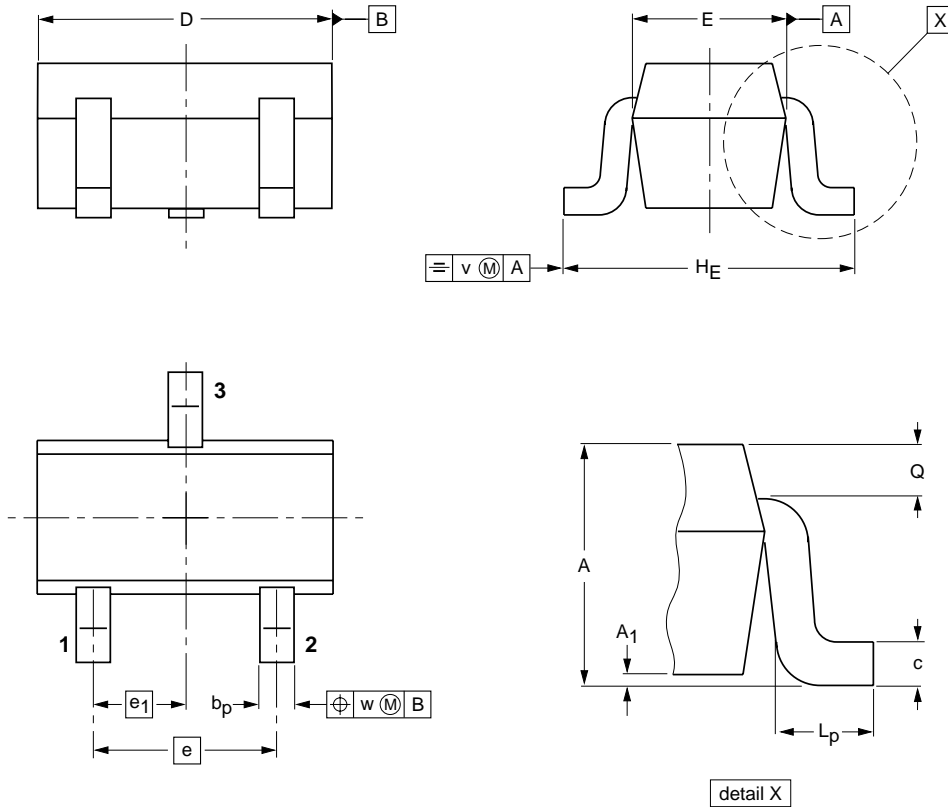


Fig. 11 Transient Thermal Response

Package Outline

SOT-523



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SOT-523	Tape/Reel, 7" reel	3000	EIA-481-1